

ABSTRACT OF THE DISCLOSURE

A semiconductor package substrate is provided having a plurality of bonding pads on at least one surface thereof and covered by a conductive film. A photoresist layer formed over the conductive film has a plurality of first openings for exposing portions of the conductive film corresponding to the bonding pads. The exposed portions of the conductive film is removed to expose the bonding pads respectively via the first openings. The exposed bonding pads are plated with a metal layer respectively. Then, the photoresist layer and the remainder of the conductive film covered by the photoresist layer are removed. A solder mask having a plurality of second openings may be formed on the surface of the substrate, and allows the plated metal layer on the bonding pads respectively to be exposed via the second openings.

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